

The mere fact that references can be combined or modified does not render the resultant combination obvious unless the prior art also suggests the desirability of the combination.  
*In re Mills*, 916 F.2d680, 16 USPQ2d 1430 (Fed. Cir. 1990)

Assuming that "*it is within the general skill of a worker in the art to discover the optimum or workable ranges on the basis of their suitability for the user's preference as a matter of obvious design choice (Office Action Page 4).*" There is no basis from the cited reference to discover Applicant's optimum workable ranges. An "Obvious to Try" modification does not establish *prima facie* obviousness (*In re Clinton*, 527, F. 2d 1226, 188USPQ 365)

In that the Office Action has failed to establish a case of *prima facie* obviousness, claims 1 – 20 are allowable over the cited reference. Applicants believe that the §103 rejections have been addressed.

Applicants have been addressed the Examiner's concerns and believe that the case is in a condition for allowance. Applicants respectfully request that it be allowed to issue.

Please charge any fees other than the issue fee and credit any overpayments to Deposit Account 14-1270.

Respectfully submitted,

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## APPENDIX A

Amended claims indicating changes made. Insertions are in underline and deletions are in ~~strikeout~~

9. *(Amended)* A method for clearing slurry from a polishing pad in a CMP process, comprising:

placing a wafer substrate in contact with a polishing pad;

rotating said polishing pad at a first speed;

dispensing slurry onto said polishing pad while said pad is rotating with said wafer substrates in contact with said pad;

terminating slurry dispense;

spraying a high pressure fluid around said wafer substrate to remove slurry from between said wafer substrate and said pad using ~~said~~ high a pressure spray portion of ~~said a~~ slurry dispense bar; and rotating said pad at a second speed during said spraying step.

## APPENDIX A (con't)

In the Specification.

Replacement paragraphs indicating changes made. Insertions are in underline and deletions are in ~~strikeout~~.

### *Page 9, Paragraph 1*

Referring now to FIGS. 6A and 6B, there will be described a method for using a slurry bar with high-pressure spray. Referring to FIG. 6A, wafers are ~~inversely~~inversely mounted on the carrier ~~ams~~ arms 430. The slurry is dispensed onto the pad 410 through a slurry dispense ~~tune~~ tube on the spray bar 420. The wafer carriers 430 bias the wafers against the pad 410. During this time both the pad 410 and the wafer carriers 430 are rotating, with the pad 410 rotating between 30 –60 ~~RPMs~~ RPM.

### *Page 10, Paragraph 4*

Additionally, referring now to FIG. 8, there is shown the prior art removal method defect density as compared to the high-pressure spray bar defect density. As shown, ~~experimentally~~ experimental use of the slurry dispense bar with high-pressure spray of the present inventions provides for a 15.15% average reduction in defect density.